

Absolute Maximum Ratings ($@T_A = +25^{\circ}C$ unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-40	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	lc	-100	mA
Peak Collector Current	Ісм	-200	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)	D	400	mW	
	(Note 6)	P _D	1,000		
Thermal Desistance Junction to Ambient	(Note 5)		310	°C/W	
Thermal Resistance, Junction to Ambient	(Note 6)	R _{θJA}	120	C/VV	
Thermal Resistance, Junction to Lead	(Note 7)	R _{θJL}	120	°C/W	
Operating and Storage and Temperature Range		T _J , T _{STG}	-55 to +150	°C	

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
	Symbol	IVIIN	wax	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)					
Collector-Base Breakdown Voltage	BV _{CBO}	-50		V	$I_{C} = -50\mu A, I_{E} = 0$
Collector-Emitter Breakdown Voltage	BV _{CEO}	-40		V	$I_{\rm C} = -1 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	-5.0	—	V	$I_E = -50 \ \mu A, \ I_C = 0$
Collector Cutoff Current	1	_	-100	nA	V _{CB} = -30V
	I _{CBO}		-5	μA	$V_{CB} = -30V, T_A = +150^{\circ}C$
Emitter Cutoff Current	I _{EBO}		-100	nA	V _{EB} = -4.0V
ON CHARACTERISTICS (Note 9)					
DC Current Gain	h _{FE}	120	270		$V_{CE} = -6.0V, I_{C} = -1.0mA$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	-0.2	V	$I_{C} = -50 \text{mA}, I_{B} = -5.0 \text{mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C _{obo}	_	5.0	pF	V _{CB} = -12V, f = 1.0MHz, I _E = 0
Current Gain-Bandwidth Product	fT	100		MHz	V_{CE} = -12V, I _C = -2.0mA, f = 100MHz

Notes: 5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.

6. Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm 2oz copper.

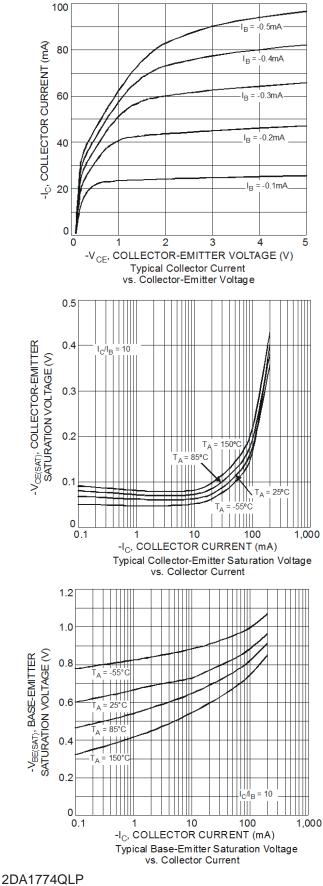
7. Thermal resistance from junction to solder-point (on the exposed collector pad).

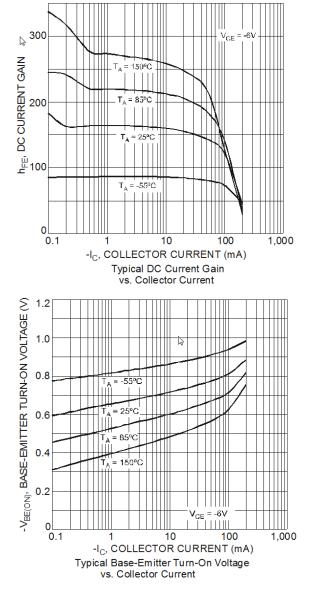
8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

9. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified)



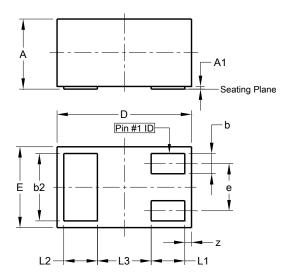


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Package Outline Dimensions

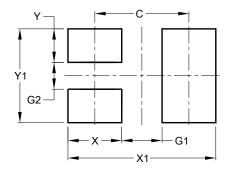
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-3				
Dim	Min	Max	Тур	
Α	0.47	0.53	0.50	
A1	0.00	0.05	0.03	
b	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.075	1.00	
Е	0.55	0.675	0.60	
е	-	-	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	-	-	0.40	
z	0.02	0.08	0.05	
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Ŷ	0.25
Y1	0.70



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